DS90UR916 Rx Demo Board - Board Stackup Revised: Friday, September 18, 2009 DS90UR916 Rx Demo Board Revision: 2 Bill Of Materials September 18,2009 18:25:53

Item	Qty Reference	Part	PCB Footprint	Comments	MFR	MFR Part#	CRITICAL	Digi-Key Part#	Lead Free?	RoHS Compliant?
2	6 C3.C7.C21.C29.C30.C34	0.1uF	CAP/HDC-0603	CAP .1UF ±10% 25V CERAMIC X7R 0603	Panasonic	ECJ-1VB1E104K		PCC2277CT-ND	YES	YES
3	5 C4.C8.C22.C25.C31	0.01uF	CAP/HDC-0603	CAP CERAMIC .01UF 100V X7R 0603	KEMET	C0603C103K1RACTU		399-3189-1-ND	YES	YES
4	4 C5.C6.C15.C16	0.1uF	CAP/HDC-0603	CAP CERAMIC .1UF 50V X7R 0603	Panasonic	ECJ-1VB1H104K	0.1uF, X7R, 50V	PCC2398CT-ND	YES	YES
5	2 C11,C14	22uF	CAP/N	CAP TANTALUM 22UF 25V 20% SMD	nichicon	F931E226MNC		493-2391-1-ND	YES	YES
6	2 C12.C17	2.2uF	3528-21 EIA	CAPACITOR TANT 2.2UF 20V 10% SMD	KEMET	T491B225K020AT		399-3714-1-ND	YES	YES
7	2 C18,C13	0.1uF	CAP/HDC-1206	CAP .10UF 50V CERAMIC X7R 1206	KEMET	C1206C104K5RACTU		399-1249-1-ND	YES	YES
8	6 C19,C20,C24,C28,C32,C33	22uF	CAP/EIA-B 3528-21	CAPACITOR TANT 22UF 16V 20% SMD	Kernet	T494B226M016AT		399-3835-1-ND	YES	YES
10	1 C26	4.7µF	CAP/HDC-0402	CAP CERAMIC 4.7UF 6.3V X5R 0402	Panasonic	ECJ-0EB0J475M		PCC2475TR-ND	YES	YES
11	2 C35,C36	5pF	CAP/HDC-0201	CAP CERAMIC 5.0PF 25V NP0 0201	Panasonic	ECJ-ZEC1E050C		PCC2107CT-ND	YES	YES
12		2-Pin Header	Header/2P	CONN HEADER VERT .100 2POS 30AU	AMP/Tyco	87220-2		A26542-ND	YES	YES
13		3-Pin Header	Header/3P	CONN HEADER VERT .100 3POS 15AU	AMP/Tyco	87224-3		A26545-ND	YES	YES
16	2 JP11,JP12	3-Pin Header	Header/3P	CONN HEADER VERT .100 3POS 15AU.	AMP/Tyco	87224-3		A26545-ND	YES	YES
18	1 J1	HSD_2X2	CON/HSD-4P	Automotive HSD Connector - Right Angle Plug for PCB	Rosenberger	D4S20B-40ML5-Y			YES	YES
19	1 J2	mini USB 5pin	mini_B_USB_surface_mount	CONN RECEPT MINI USB2.0 5POS.	Hirose	UX60-MB-5ST		H2959CT-ND	YES	YES
20	1 J3	IDC1X4	IDC-1x4	CONN HEADER 4POS .100 VERT GOLD	Molex/Waldom Electronics Corp	22-11-2042		WM2702-ND	YES	YES
21	2 J4,J5	BANANA	CON/BANANA-S	BANANA-female (non-insulated)	Johnson	108-0740-001		J147-ND	YES	YES
26	1 LED1	0402_orange_LED	0402 SMT	LED ORN/CLEAR 610NM 0402 SMD	Lumex Opto/Components Inc	SML-LX0402SOC-TR		67-1879-1-ND	YES	YES
27	1 LED2	0603_green_LED	0603 (Super Thin)	LED GREEN CLEAR THIN 0603 SMD	LITE-ON INC	LTST-C191KGKT		160-1446-1-ND	YES	YES
28	1 P1	HEADER 28x2	2x28 0.1"	CONN HEADER VERT 56POS .100 30AU. Cut 60 POS or use AMP part #2-87215-9.	AMP/TYCO	3-87215-0		A26588-ND	YES	YES
32	4 R31,R37,R38,R39	10K	RES/HDC-0603	RES 10.0K OHM 1/10W 1% 0603 SMD	Panasonic	ERJ-3EKF1002V		P10.0KHCT-ND	YES	YES
33	1 R32	470 Ohm	RES/HDC-0603	RES 470 OHM 1/10W 1% 0603 SMD	Panasonic	ERJ-3EKF4700V		P470HCT-ND	YES	YES
37	8 R40,R43,R44,R45,R46,R47, R59,R60	0 Ohm,0402	RES/HDC-0402	RES ZERO OHM 1/16W 5% 0402 SMD	Panasonic	ERJ-2GEJ0R00X		P0.0JTR-ND	YES	YES
40	1 R56	0 ohm	RES/HDC-0201	RES 0.0 OHM 1/20W 5% 0201 SMD.	Panasonic	ERJ-1GE0R00C		P0.0AGCT-ND	YES	YES
41	2 R62,R61	4.7K	RES/HDC-0603	RES 4.7K OHM 1/10W 5% 0603 SMD	Panasonic	ERJ-3GEYJ472V		P4.7KGCT-ND	YES	YES
42	1 S1	SW DIP-3	DIP-6	SWITCH DIP EXTENDED SEALED 3POS	Grayhill	78B03ST		GH7182-ND	YES	YES
43	1 U1	DS90UR916	60ld LLP	FPD-Link II Deserializer with Image Enhancement	TI	DS90UR916QSE			YES	YES

## 63 TOTAL COMPONENT COUNT

Note: modify solder mask: VR3 - component not stuffed R32 - component stuffed R57, R58 - component not stuffed

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